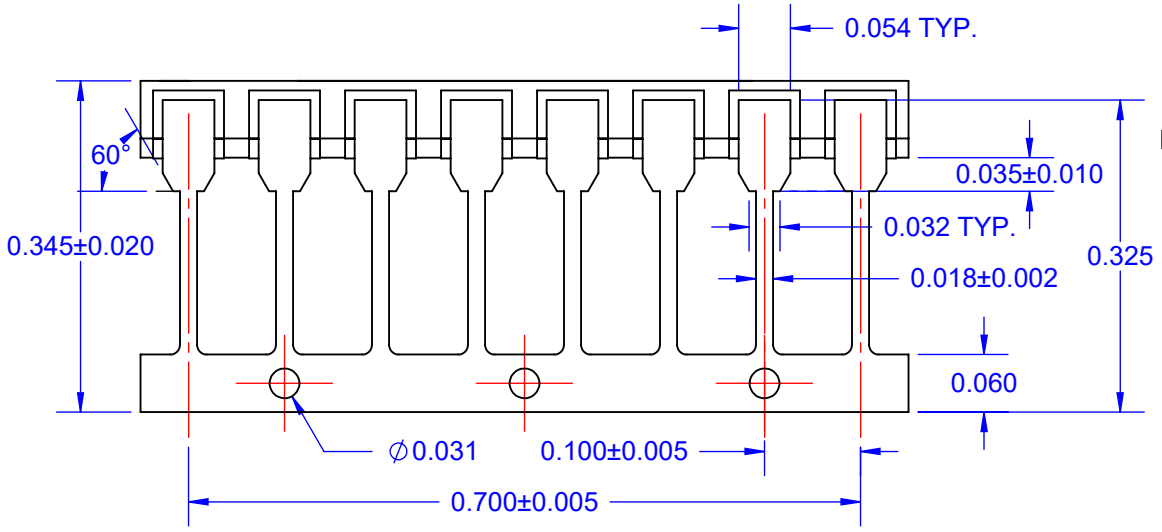


DETAIL B
SCALE 10 : 1

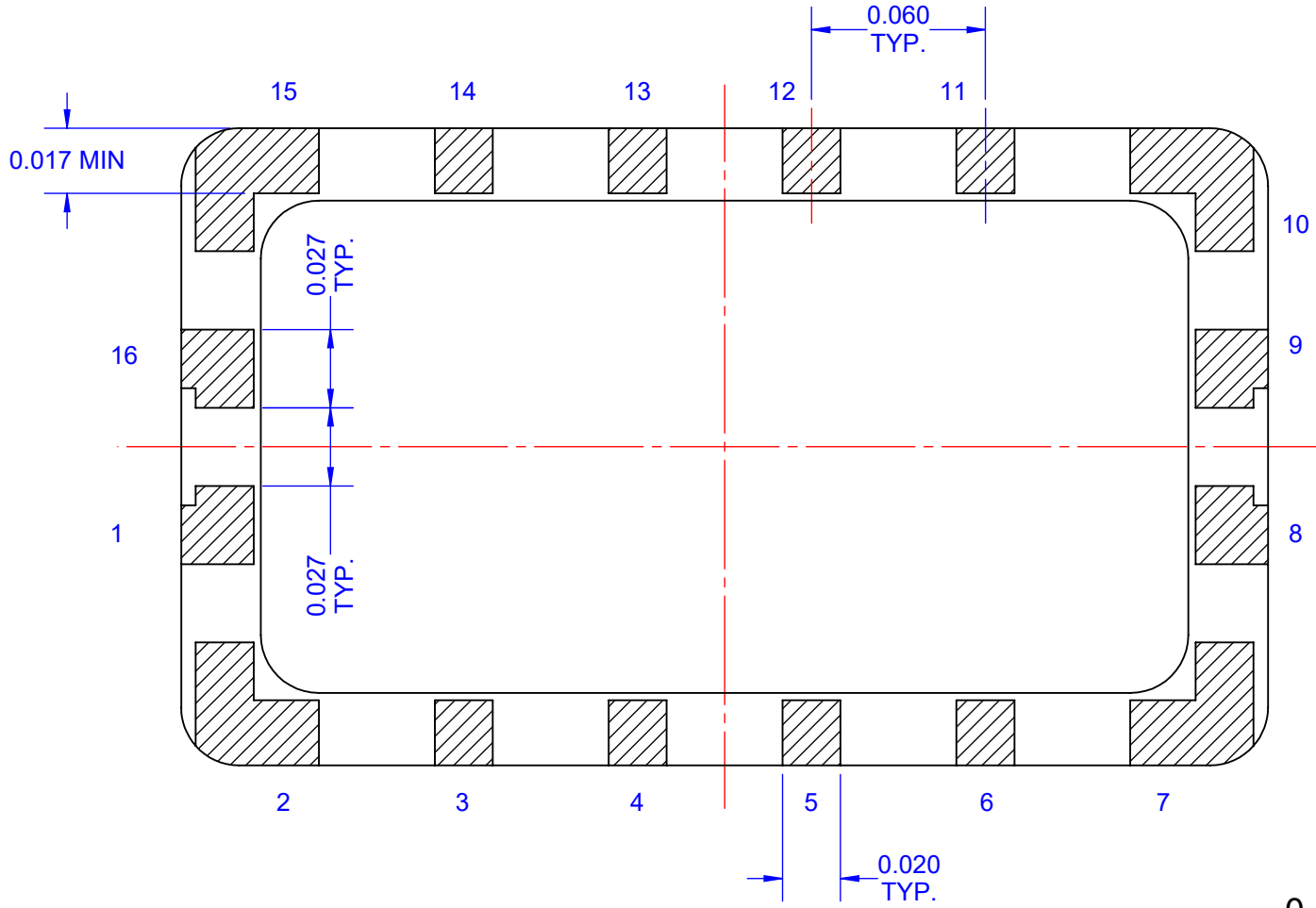


- NOTES: (Unless Otherwise Specified).
1. GOLD PLATE 60 micro-inch over 100 micro-inch (MIN) NICKEL.
 2. SEAL AREA TO BE METALLIZED.
 3. SEE PART NUMBER TABLE FOR DIE ATTACH METALLIZATION.
 4. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.
 5. LEAD RESISTANCE: 0.20 OHM MAX.
 6. TOLERANCE ± 0.005 -INCH UNLESS OTHERWISE SPECIFIED.
 7. CERAMIC (Al_2O_3 BLACK) SIDE-BRAZE PACKAGE KOVAR LEAD FRAME WITH GOLD METALLIZATION.

PART NUMBER TABLE		
PART NUMBER	DIE PAD	DWG
CERDIP16F3-SB-N170x320	GOLD	161732

APPROVALS	DATE	TopLine [®]			
DRAWN T. Au	6/21/2021				
ENG M. Hart	6/21/2021	TITLE CERDIP16F3-SB-N170x320 DIE PAD 4.3 x 8.1mm			
MFG		SCALE	SIZE	DRAWING NO.	REV
QA		5:1	A	161732	A
CUST		DO NOT SCALE DRAWING			SHEET 1 OF 4
REVISED					

BONDING PADS

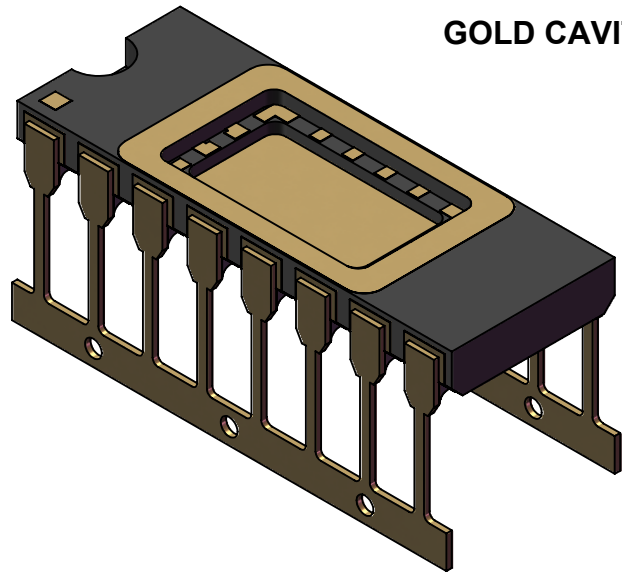


DIE PAD
 0.170 x 0.320-inch
 4.3 x 8.1mm

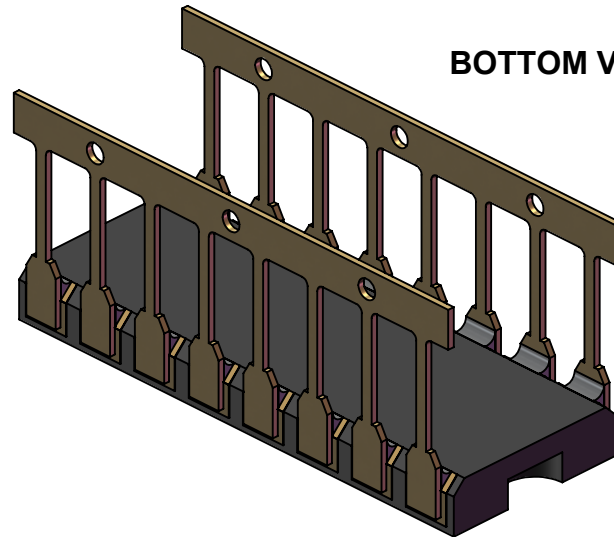
PART NUMBER TABLE		
PART NUMBER	DIE PAD	DWG
CERDIP16F3-SB-N170x320	GOLD	161732

TopLine®			
TITLE CERDIP16F3-SB-N170x320 DIE PAD 4.3 x 8.1mm			
SCALE 5:1	SIZE A	DRAWING NO. 161732	REV A
DO NOT SCALE DRAWING			SHEET 2 OF 4

MODELS



GOLD CAVITY



BOTTOM VIEW

PART NUMBER TABLE		
PART NUMBER	DIE PAD	DWG
CERDIP16F3-SB-N170x320	GOLD	161732

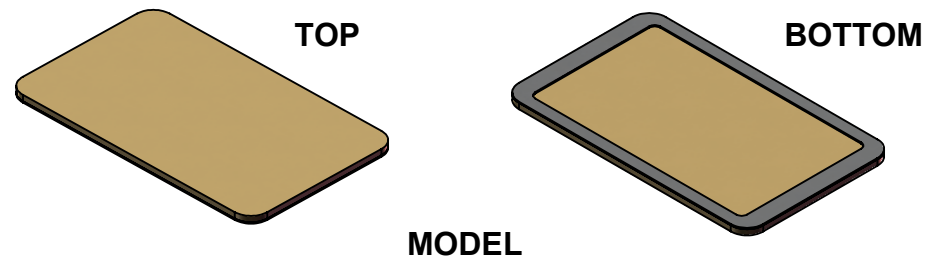
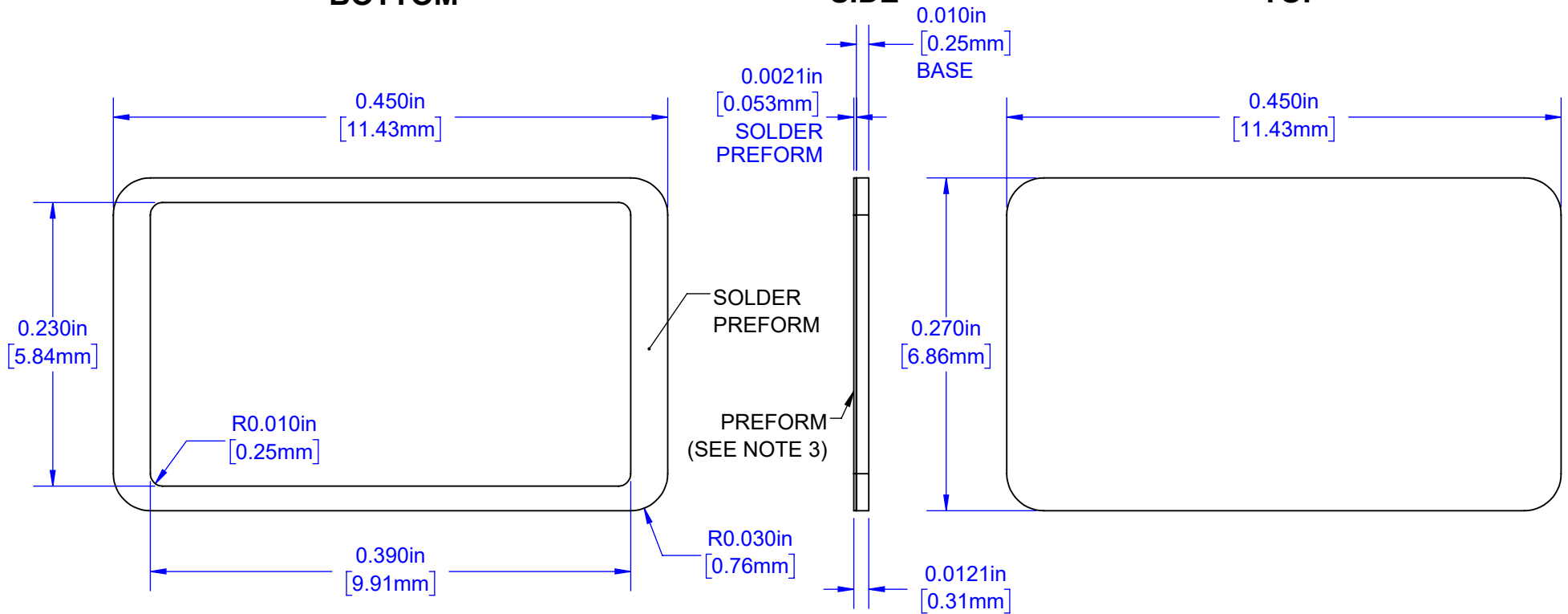
TopLine[®]			
TITLE CERDIP16F3-SB-N170x320 DIE PAD 4.3 x 8.1mm			
SCALE 5:1	SIZE A	DRAWING NO. 161732	REV A
DO NOT SCALE DRAWING			SHEET 3 OF 4

COMBO LID OPTIONAL

BOTTOM

SIDE

TOP



NOTES:

1. BASE MATERIAL: KOVAR or ALLOY 42.
2. PLATING: Ni 50~350 MICRO-INCH PER SIDE.
Au 25 MICRO-INCH MIN PER SIDE.
3. SOLDER PREFORM: Au 80% ± 1.0 Sn 20%.
4. FLATNESS 1.0 MIL (25µm) MAXIMUM PER 0.5-inch (12.7mm).

REF: W1272H

MODEL

TopLine®			
TITLE		CL-270x450-A COMBO LID	
SCALE	SIZE	DRAWING NO.	REV
8:1	A	148857	A
DO NOT SCALE DRAWING			SHEET 4 OF 4